

June 2007

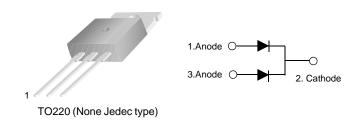
## FYP1010DN

## **Schottky Barrier Rectifier**

- Low forward voltage drop
- High frequency properties and switching speed
- Guard ring for over-voltage protection

## **Applications**

- Switched mode power supply
- Freewheeling diodes



## Absolute Maximum Ratings \*T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>RRM</sub>	Maximum Repetitive Reverse Voltage	100	V
V <sub>R</sub>	Maximum DC Reverse Voltage	100	V
I <sub>F(AV)</sub>	Average Rectified Forward Current @ T <sub>C</sub> = 135°C	10	Α
I <sub>FSM</sub>	Non-repetitive Peak Surge Current (per diode) 60Hz Single Half-Sine Wave	100	А
T <sub>J,</sub> T <sub>STG</sub>	Operating Junction and Storage Temperature	-65 to +150	°C

### **Thermal Characteristics**

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case (per diode)	2.5	°C/W

## Electrical Characteristics (per diode)

Symbol	Parameter		Value	Units
V <sub>FM</sub> *	Maximum Instantaneous Forward Voltage $I_F = 5A$ $I_F = 5A$ $I_F = 10A$ $I_F = 10A$	$T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 125 ^{\circ}\text{C}$ $T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 125 ^{\circ}\text{C}$	0.75 0.65 0.95 0.73	V
I <sub>RM</sub> *	Maximum Instantaneous Reverse Current @ rated V <sub>R</sub>	$T_C = 25  ^{\circ}C$ $T_C = 125  ^{\circ}C$	1 30	mA

<sup>\*</sup> Pulse Test: Pulse Width=300μs, Duty Cycle=2%

## **Typical Performance Characteristics**

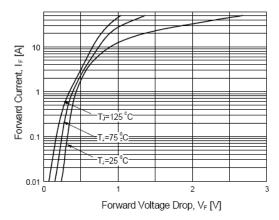


Figure 1. Typical Forward Voltage Characteristics (per diode)

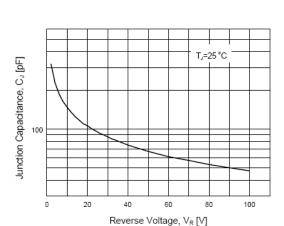


Figure 3. Typical Junction Capacitance (per diode)

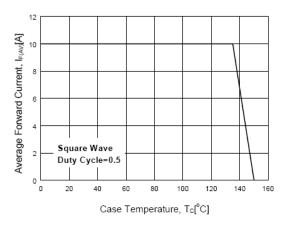


Figure 5. Forward Current Derating Curve

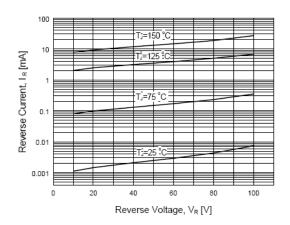


Figure 2. Typical Reverse Current vs. Reverse Voltage (per diode)

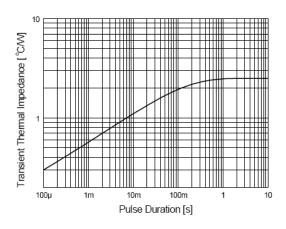


Figure 4. Thermal Impedance Characteristics (per diode)

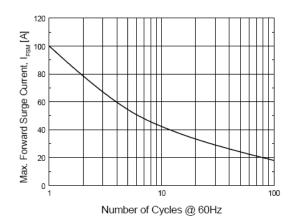
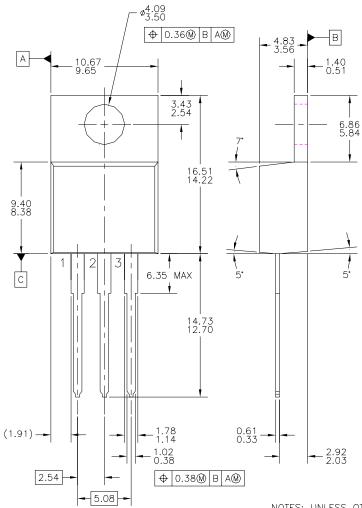
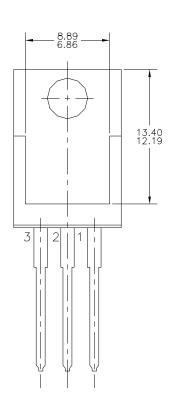


Figure 6. Non-Repetive Sureg Current (per diode)

# **Package Dimensions**

# TO-220





NOTES: UNLESS OTHERWISE SPECIFIED

- REFERENCE JEDEC, TO-220, ISSUE K, VARIATION AB, DATED APRIL, 2002.
- ALL DIMENSIONS ARE IN MILLIMETERS.
  DIMENSIONING AND TOLERANCING PER
- C)
- ANSI Y14.5 1973 LOCATION OF THE PIN HOLE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE)

TO220B03REVD

**Dimensions in Millimeters** 





UniFET™

 $VCX^{TM}$ 

Wire™

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